# Monthly LabAdviser update: 26/10 2017

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| Updated Subject  | Contributor | Link to the updated pages |
| **ASE equipment page**New gasses have been added | **Berit Herstrøm @danchip**  | [ASE\_(Advanced\_Silicon\_Etch)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ASE_%28Advanced_Silicon_Etch%29) |
| **DRIE Pegasus**Etch high aspect ratio silicon microstructures | **Bingdong Chang @danchip** | [DRIE-Pegasus/Etch\_high\_aspect\_ratio\_silicon\_microstructures](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Etch_high_aspect_ratio_silicon_microstructures) |
| **DRIE Pegasus**Etch 3 dimensional silicon microstructures | **Bingdong Chang @danchip** | [DRIE-Pegasus/Etch\_3\_dimensional\_silicon\_microstructures](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Etch_3_dimensional_silicon_microstructures) |
| **DRIE Pegasus**Etch black silicon | **Bingdong Chang @danchip** | [DRIE-Pegasus/Etch\_black\_silicon](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Etch_black_silicon) |
| **DRIE Pegasus**Using OES to monitor etch process | **Bingdong Chang @danchip** | [DRIE-Pegasus/Using\_OES\_to\_monitor\_etch\_process](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Using_OES_to_monitor_etch_process) |
| **E-beam lithography**High resolution patterning with HSQ | **Bingdong Chang @danchip** | [EBeamLithography/High\_resolution\_patterning\_with\_HSQ](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/EBeamLithography/High_resolution_patterning_with_HSQ) |
| **ALD2**Deposition of thermal TiN at 500 degrees | **Evgeniy Shkondin @fotonik** **Pernille V. Larsen @danchip** | [ALD2\_(PEALD)/TiN\_deposition\_using\_ALD2#Deposition\_of\_thermal\_TiN\_using\_TMA\_and\_NH3\_precursors](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/ALD2_%28PEALD%29/TiN_deposition_using_ALD2#Deposition_of_thermal_TiN_using_TMA_and_NH3_precursors) |
| **Thermal Evaporator**Equipment page for the new thermal evaporator (not released yet) | **Mikkel Mar ~~@danchip~~****(is not here anymore)** | [Thin\_film\_deposition/thermalevaporator](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/thermalevaporator)[Deposition\_of\_Aluminium#Thermal\_deposition\_of\_Aluminium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium#Thermal_deposition_of_Aluminium) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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|  | **Manual for Hotplate (SU8)** |
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|  | **Manual for Resist Pyrolysis Furnace** |
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|  | **Manual for Boron Drive-in + Pre-dep Furnace (A1)** |
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|  | **Manual for Furnace: Multipurpose Annealing** |
|  | **Manual for SEM Supra 3** |
|  | **Manual for III-V Plasma Asher\_ Pico.** |